Supplementary Information

Promotion of Mo-based ionic crystal precursor for MoS₂ wafer growth

Jinxiu Liu, Chunchi Zhang, Yan Huang, Haijuan Wu, Chao Tan, Zegao Wang* College of Materials Science and Engineering, Sichuan University, Chengdu 610065, China

Corresponding author: Zegao Wang, zegao@scu.edu.cn



Figure S1 (a) The optical image of the 2-inch MoS_2 film grown using Na_2MoO_4 . (b-f) The optical image was measured evenly at 5 locations on a 2-inch wafer. The scale bar is 100 μ m.



Figure S2 $(NH_4)_2MoO_4$ as ion precursor has been adopted to grow wafer-scale MoS_2 film. (a) The photo of the 2-inch MoS_2 film grown using $(NH_4)_2MoO_4$. (b) The optical image of wafer-scale MoS_2 films using $(NH_4)_2MoO_4$ show high continuity and uniformity. The scale bar is 100 µm. (c) Raman spectra of MoS_2 using $(NH_4)_2MoO_4$ could also reflect the uniformity show in different marks shown in Figure S2a.



Figure S3 (a) XPS survey spectrum and (b) high-resolution Na 1s XPS spectra of $\rm MoS_2$ using $\rm Na_2MoO_4$



Figure S4 The temperature-time (T-t) curve (black) and different growth time interval (filled in red) in wafer-scale MoS_2 growth. In the early stage of growth is a linear heating stage, molybdenum source and sulfur source remain inert. After 800°C insulation, molybdenum source and sulfur source began to be active. Rapid growth happens at the holding temperature. Finally, the chamber naturally cools to

room temperature. the scale bar is 20 μ m in Figure S1(b-g) optical images .



Figure S5 AFM images of monolayer MoS_2 wafer in different areas. (a) The optical image of the 2inch MoS_2 film grown using Na_2MoO_4 . (b-f) The AFM image was measured evenly at 5 locations on a 2-inch wafer. The scale bar is 2 μ m.



Figure S6 Transfer and device fabrication of wafer-scale monolayer MoS_2 . (a) 2-inch wafer MoS_2 on sapphire (Figure S3a(i)) has been transferred to 285 nm SiO₂/Si in Fig S3a(ii). (b) the optical images of MoS_2 are shown in the Figure 3b. (c) the source and drain electrodes (Ti/Au, 20/30 nm) were defined on MoS_2 by photolithography, electron-beam evaporation and vacuum metallization for smaller ohmic contact resistance.